

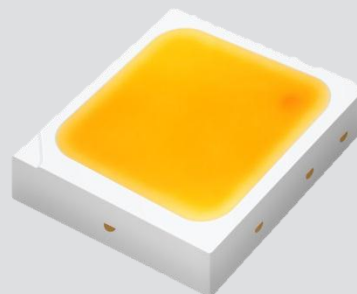


**THE DATASHEET OF  
SPMWHT327FD7GBQKS0**



Middle Power LED Series  
3030

# LM302A CRI 90



LM302A leads lighting design trend with high performance and efficacy

## Features & Benefits

- 1 W class middle-high power LED
- EMC resin for high reliability
- Standard form factor for design flexibility
- High performance and efficacy



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## 1. Characteristics

### a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Operating Temperature	$T_a$	-40 ~ +85	°C	-
Storage Temperature	$T_{stg}$	-40 ~ +100	°C	-
LED Junction Temperature	$T_j$	125	°C	-
Forward Current	$I_F$	200	mA	-
Assembly Process Temperature	-	260 <10	°C s	-
ESD (HBM)	-	5	kV	-

**b) Electro-optical Characteristics (I<sub>F</sub> = 150 mA, T<sub>s</sub> = 85 °C)**

Item	Nominal CCT (K)	Rank	Bin	Min.	Typ.	Max.	Unit
Forward Voltage (V <sub>F</sub> )		YB	BY	5.6	-	5.8	V
			BZ	5.8	-	6.0	
			B1	6.0	-	6.2	
			B2	6.2	-	6.4	
			B3	6.4	-	6.6	
Luminous Flux (Φ <sub>v</sub> )	2700	S0	S1	80.0	-	88.0	lm
			S2	88.0	-	96.0	
	3000	S0	S1	85.0	-	93.0	
			S2	93.0	-	101.0	
	3500	S0	S1	86.8	-	94.8	
			S2	94.8	-	102.8	
	4000	S0	S1	88.6	-	96.6	
			S2	96.6	-	104.6	
	5000	S0	S1	86.8	-	94.8	
			S2	94.8	-	102.8	
	5700	S0	S1	85.0	-	93.0	
			S2	93.0	-	101.0	
	6500	S0	S1	83.2	-	91.2	
			S2	91.2	-	99.2	
Reverse Voltage (@ 5 mA)				0.7	-	1.2	V
Color Rendering Index (R <sub>a</sub> )				90	-	-	-
Special CRI (R9)				50	-	-	-
Thermal Resistance (junction to solder point)				-	12	-	°C/W
Beam Angle				-	120	-	°

**Note:**

Samsung maintains measurement tolerance of: forward voltage = ±0.1 V, luminous flux = ±5 %, CRI = ±3, R9 = ±6.5

## 2. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	P	M	W	H	T	3	2	7	F	D	7	Y	B	W	0	S	0

Digit	PKG Information	Code	Specification
1 2 3	Samsung Package Middle Power	<b>SPM</b>	
4 5	Color	<b>WH</b>	White
6	Product Version	<b>T</b>	
7 8 9	Form Factor	<b>327</b>	3.0 x 3.0 x 0.65 mm; 2 pads; 2 chips
10	Sorting Current	<b>F</b>	150 mA
11	Chromaticity Coordinates	<b>D</b>	ANSI Standard
12	CRI	<b>7</b>	Min. 90
13 14	Forward Voltage (V)	<b>YB</b>	5.6~6.6 Bin Code: <b>BY</b> 5.6~5.8 <b>BZ</b> 5.8~6.0 <b>B1</b> 6.0~6.2 <b>B2</b> 6.2~6.4 <b>B3</b> 6.4~6.6
15 16	CCT (K)	<b>W</b> ☆ <b>V</b> ☆ <b>U</b> ☆ <b>T</b> ☆ <b>R0</b> <b>Q0</b> <b>P0</b>	2700 3000 3500 4000 5000 5700 6500 W1, W2, W3, W4, W5, W6, W7, W8, W9, WA, WB, WC, WD, WE, WF, WG V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG R1, R2, R3, R4, R7, R8 Q1, Q2, Q3, Q4, Q7, Q8 P1, P2, P3, P4, P7, P8 ☆ : "0" (Whole bin) or "M" (Quarter bin)
17 18	Luminous Flux (lm)	<b>S0</b>	Bin Code: S1, S2

a) Luminous Flux Bins ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )

Nominal CCT (K)	CRI Min.	Product Code	Flux Bin	Flux Range ( $\Phi_v$ , lm)
2700	90	SPMWHT327FD7YBW☆S0	S1	80.0 ~ 88.0
			S2	88.0 ~ 96.0
3000	90	SPMWHT327FD7YBV☆S0	S1	85.0 ~ 93.0
			S2	93.0 ~ 101.0
3500	90	SPMWHT327FD7YBU☆S0	S1	86.8 ~ 94.8
			S2	94.8 ~ 102.8
4000	90	SPMWHT327FD7YBT☆S0	S1	88.6 ~ 96.6
			S2	96.6 ~ 104.6
5000	90	SPMWHT327FD7YBR0S0	S1	86.8 ~ 94.8
			S2	94.8 ~ 102.8
5700	90	SPMWHT327FD7YBQ0S0	S1	85.0 ~ 93.0
			S2	93.0 ~ 101.0
6500	90	SPMWHT327FD7YBP0S0	S1	83.2 ~ 91.2
			S2	91.2 ~ 99.2

**Note:**

"☆" can be "0" (Whole bin) or "M" (Quarter bin) of the color binning

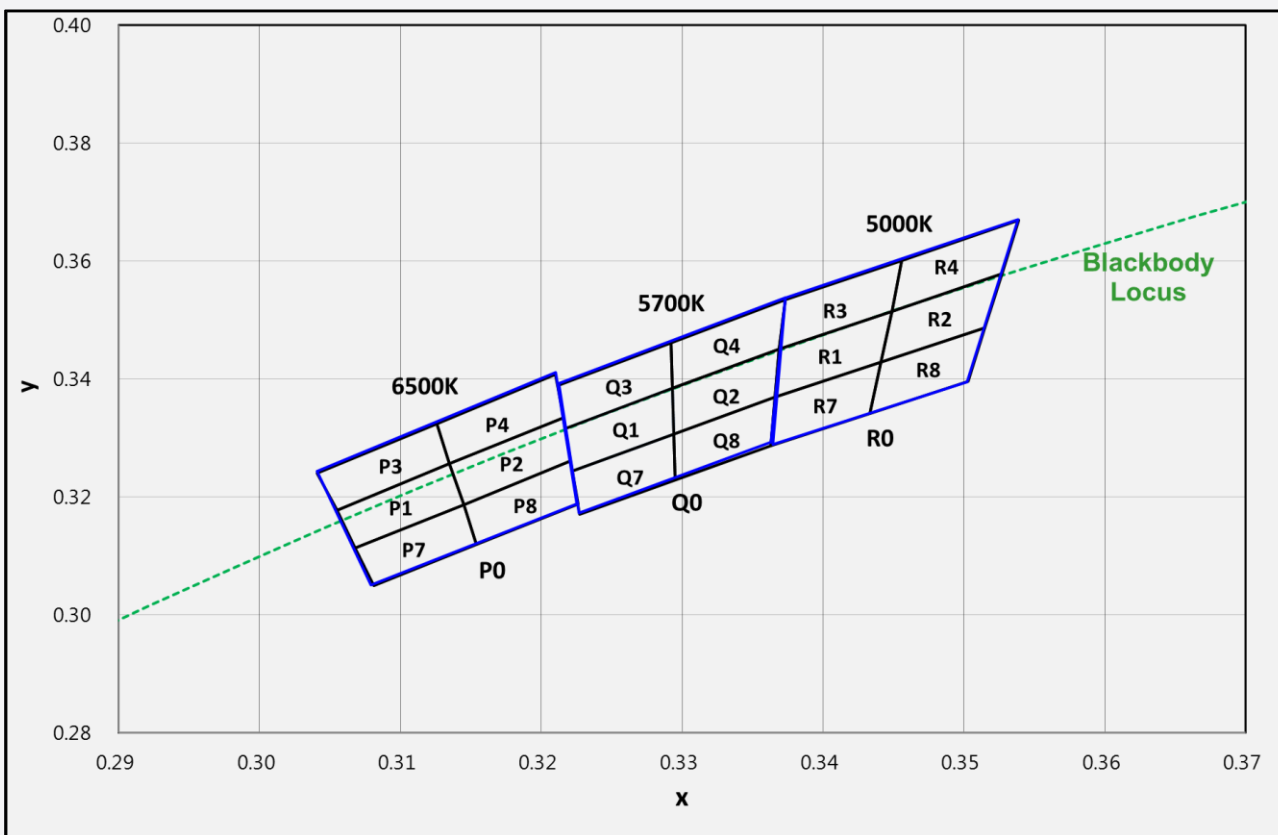
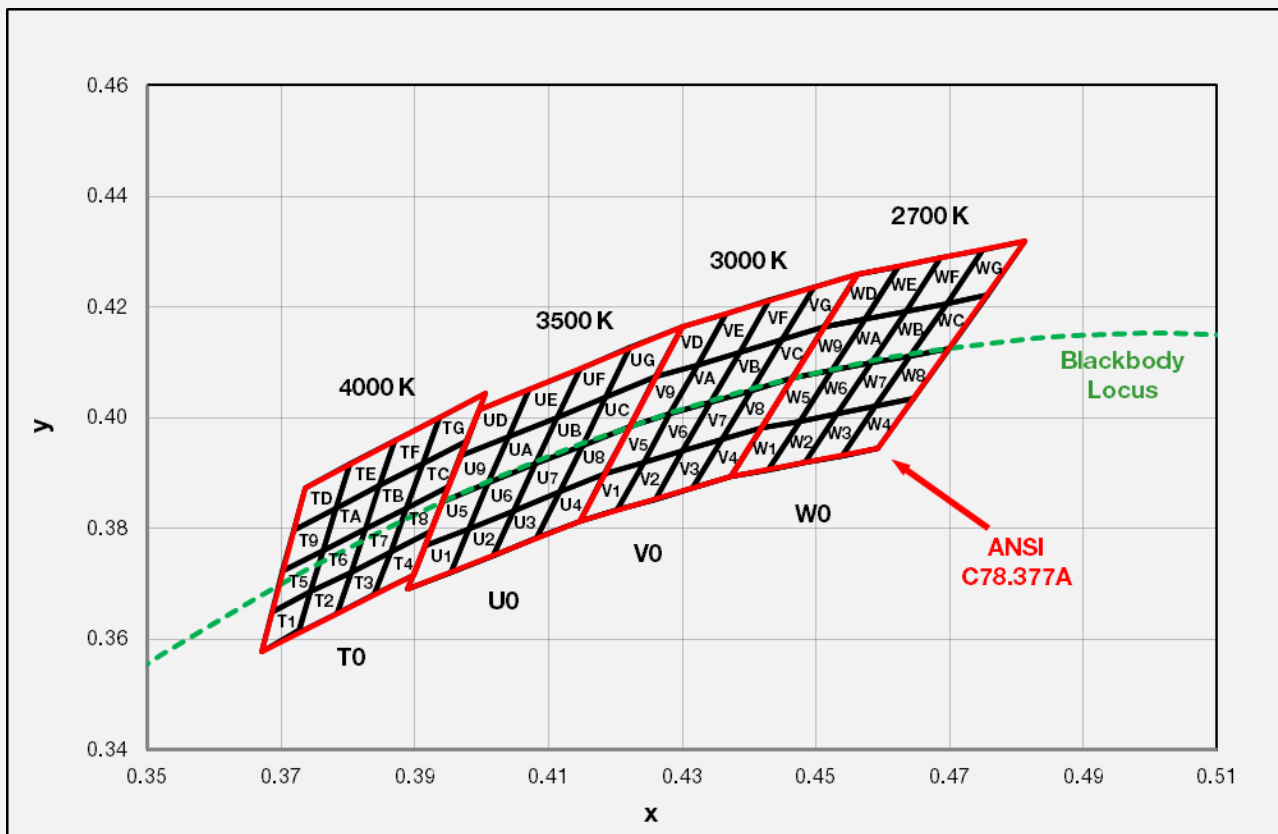
b) Color Bins ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )

Nominal CCT (K)	CRI Min.	Product Code	Color Rank	Chromaticity Bins
2700	90	SPMWHT327FD7YBW0S0	W0 (Whole bin)	W1, W2, W3, W4, W5, W6, W7, W8, W9, WA, WB, WC, WD, WE, WF, WG
		SPMWHT327FD7YBWMS0	WM (Quarter bin)	W6, W7, WA, WB
3000	90	SPMWHT327FD7YBV0S0	V0 (Whole bin)	V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG
		SPMWHT327FD7YBVMS0	VM (Quarter bin)	V6, V7, VA, VB
3500	90	SPMWHT327FD7YBU0S0	U0 (Whole bin)	U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG
		SPMWHT327FD7YBUMS0	UM (Quarter bin)	U6, U7, UA, UB
4000	90	SPMWHT327FD7YBT0S0	T0 (Whole bin)	T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG
		SPMWHT327FD7YBTMS0	TM (Quarter bin)	T6, T7, TA, TB
5000	90	SPMWHT327FD7YBR0S0	R0 (Whole bin)	R1, R2, R3 R4, R7, R8
5700	90	SPMWHT327FD7YBQ0S0	Q0 (Whole bin)	Q1, Q2, Q3 Q4, Q7, Q8
6500	90	SPMWHT327FD7YBP0S0	P0 (Whole bin)	P1, P2, P3, P4, P7, P8

c) Voltage Bins ( $I_f = 150 \text{ mA}$ ,  $T_s = 85 \text{ °C}$ )

Nominal CCT (K)	CRI Min.	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
-	-	-	YB	BY	5.6 ~ 5.8
				BZ	5.8 ~ 6.0
				B1	6.0 ~ 6.2
				B2	6.2 ~ 6.4
				B3	6.4 ~ 6.6

d) Chromaticity Region & Coordinates ( $I_f = 150 \text{ mA}$ ,  $T_s = 85^\circ\text{C}$ )



**d) Chromaticity Region & Coordinates ( $I_F = 150 \text{ mA}$ ,  $T_s = 85 \text{ }^\circ\text{C}$ )**

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>W rank (2700 K)</b>					
W1	0.4373	0.3893	W9	0.4465	0.4071
	0.4418	0.3981		0.4513	0.4164
	0.4475	0.3994		0.4573	0.4178
	0.4428	0.3906		0.4523	0.4085
W2	0.4428	0.3906	WA	0.4523	0.4085
	0.4475	0.3994		0.4573	0.4178
	0.4532	0.4008		0.4634	0.4193
	0.4483	0.3919		0.4582	0.4099
W3	0.4483	0.3919	WB	0.4582	0.4099
	0.4532	0.4008		0.4634	0.4193
	0.4589	0.4021		0.4695	0.4207
	0.4538	0.3931		0.4641	0.4112
W4	0.4538	0.3931	WC	0.4641	0.4112
	0.4589	0.4021		0.4695	0.4207
	0.4646	0.4034		0.4756	0.4221
	0.4593	0.3944		0.4700	0.4126
W5	0.4418	0.3981	WD	0.4513	0.4164
	0.4465	0.4071		0.4562	0.4260
	0.4523	0.4085		0.4624	0.4274
	0.4475	0.3994		0.4573	0.4178
W6	0.4475	0.3994	WE	0.4573	0.4178
	0.4523	0.4085		0.4624	0.4274
	0.4582	0.4099		0.4687	0.4289
	0.4532	0.4008		0.4634	0.4193
W7	0.4532	0.4008	WF	0.4634	0.4193
	0.4582	0.4099		0.4687	0.4289
	0.4641	0.4112		0.4750	0.4304
	0.4589	0.4021		0.4695	0.4207
W8	0.4589	0.4021	WG	0.4695	0.4207
	0.4641	0.4112		0.4750	0.4304
	0.4700	0.4126		0.4813	0.4319
	0.4646	0.4034		0.4756	0.4221

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>V rank (3000 K)</b>					
V1	0.4147	0.3814	V9	0.4221	0.3984
	0.4183	0.3898		0.4259	0.4073
	0.4242	0.3919		0.4322	0.4096
	0.4203	0.3833		0.4281	0.4006
V2	0.4203	0.3833	VA	0.4281	0.4006
	0.4242	0.3919		0.4322	0.4096
	0.4300	0.3939		0.4385	0.4119
	0.4259	0.3853		0.4342	0.4028
V3	0.4259	0.3853	VB	0.4342	0.4028
	0.4300	0.3939		0.4385	0.4119
	0.4359	0.3960		0.4449	0.4141
	0.4316	0.3873		0.4403	0.4049
V4	0.4316	0.3873	VC	0.4403	0.4049
	0.4359	0.3960		0.4449	0.4141
	0.4418	0.3981		0.4513	0.4164
	0.4373	0.3893		0.4465	0.4071
V5	0.4183	0.3898	VD	0.4259	0.4073
	0.4221	0.3984		0.4299	0.4165
	0.4281	0.4006		0.4364	0.4188
	0.4242	0.3919		0.4322	0.4096
V6	0.4242	0.3919	VE	0.4322	0.4096
	0.4281	0.4006		0.4364	0.4188
	0.4342	0.4028		0.4430	0.4212
	0.4300	0.3939		0.4385	0.4119
V7	0.4300	0.3939	VF	0.4385	0.4119
	0.4342	0.4028		0.4430	0.4212
	0.4403	0.4049		0.4496	0.4236
	0.4359	0.3960		0.4449	0.4141
V8	0.4359	0.3960	VG	0.4449	0.4141
	0.4403	0.4049		0.4496	0.4236
	0.4465	0.4071		0.4562	0.4260
	0.4418	0.3981		0.4513	0.4164

## d) Chromaticity Region &amp; Coordinates

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>U rank (3500 K)</b>					
U1	0.3889	0.3690	U9	0.3941	0.3848
	0.3915	0.3768		0.3968	0.3930
	0.3981	0.3800		0.4040	0.3966
	0.3953	0.3720		0.4010	0.3882
U2	0.3953	0.3720	UA	0.4010	0.3882
	0.3981	0.3800		0.4040	0.3966
	0.4048	0.3832		0.4113	0.4001
	0.4017	0.3751		0.4080	0.3916
U3	0.4017	0.3751	UB	0.4080	0.3916
	0.4048	0.3832		0.4113	0.4001
	0.4116	0.3865		0.4186	0.4037
	0.4082	0.3782		0.4150	0.3950
U4	0.4082	0.3782	UC	0.4150	0.3950
	0.4116	0.3865		0.4186	0.4037
	0.4183	0.3898		0.4259	0.4073
	0.4147	0.3814		0.4221	0.3984
U5	0.3915	0.3768	UD	0.3968	0.3930
	0.3941	0.3848		0.3996	0.4015
	0.4010	0.3882		0.4071	0.4052
	0.3981	0.3800		0.4040	0.3966
U6	0.3981	0.3800	UE	0.4040	0.3966
	0.4010	0.3882		0.4071	0.4052
	0.4080	0.3916		0.4146	0.4089
	0.4048	0.3832		0.4113	0.4001
U7	0.4048	0.3832	UF	0.4113	0.4001
	0.4080	0.3916		0.4146	0.4089
	0.4150	0.3950		0.4222	0.4127
	0.4116	0.3865		0.4186	0.4037
U8	0.4116	0.3865	UG	0.4186	0.4037
	0.4150	0.3950		0.4222	0.4127
	0.4221	0.3984		0.4299	0.4165
	0.4183	0.3898		0.4259	0.4073

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>T rank (4000 K)</b>					
T1	0.3670	0.3578	T9	0.3702	0.3722
	0.3726	0.3612		0.3763	0.3760
	0.3744	0.3685		0.3782	0.3837
	0.3686	0.3649		0.3719	0.3797
T2	0.3726	0.3612	TA	0.3763	0.3760
	0.3783	0.3646		0.3825	0.3798
	0.3804	0.3721		0.3847	0.3877
	0.3744	0.3685		0.3782	0.3837
T3	0.3783	0.3646	TB	0.3825	0.3798
	0.3840	0.3681		0.3887	0.3836
	0.3863	0.3758		0.3912	0.3917
	0.3804	0.3721		0.3847	0.3877
T4	0.3840	0.3681	TC	0.3887	0.3837
	0.3898	0.3716		0.3950	0.3875
	0.3924	0.3794		0.3978	0.3958
	0.3863	0.3758		0.3912	0.3917
T5	0.3686	0.3649	TD	0.3719	0.3797
	0.3744	0.3685		0.3782	0.3837
	0.3763	0.3760		0.3802	0.3916
	0.3702	0.3722		0.3736	0.3874
T6	0.3744	0.3685	TE	0.3782	0.3837
	0.3804	0.3721		0.3847	0.3877
	0.3825	0.3798		0.3869	0.3958
	0.3763	0.376		0.3802	0.3916
T7	0.3804	0.3721	TF	0.3847	0.3877
	0.3863	0.3758		0.3912	0.3917
	0.3887	0.3836		0.3937	0.4001
	0.3825	0.3798		0.3869	0.3958
T8	0.3863	0.3758	TG	0.3912	0.3917
	0.3924	0.3794		0.3978	0.3958
	0.3950	0.3875		0.4006	0.4044
	0.3887	0.3836		0.3937	0.4001

## d) Chromaticity Region &amp; Coordinates

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>R rank (5000 K)</b>					
R1	0.3366	0.3369	R4	0.3449	0.3515
	0.3441	0.3428		0.3527	0.3578
	0.3449	0.3515		0.3539	0.3669
	0.3369	0.3451		0.3456	0.3601
R2	0.3441	0.3428	R7	0.3363	0.3287
	0.3515	0.3487		0.3433	0.3341
	0.3527	0.3578		0.3441	0.3428
	0.3449	0.3515		0.3366	0.3369
R3	0.3369	0.3451	R8	0.3433	0.3341
	0.3449	0.3515		0.3503	0.3396
	0.3456	0.3601		0.3515	0.3487
	0.3373	0.3534		0.3441	0.3428

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>Q rank (5700 K)</b>					
Q1	0.3222	0.3243	Q4	0.3293	0.3384
	0.3294	0.3306		0.3369	0.3451
	0.3293	0.3384		0.3373	0.3534
	0.3217	0.3316		0.3292	0.3461
Q2	0.3294	0.3306	Q7	0.3227	0.3170
	0.3366	0.3369		0.3295	0.3228
	0.3369	0.3451		0.3294	0.3306
	0.3293	0.3384		0.3222	0.3243
Q3	0.3217	0.3316	Q8	0.3295	0.3228
	0.3293	0.3384		0.3363	0.3287
	0.3292	0.3461		0.3366	0.3369
	0.3212	0.3389		0.3294	0.3306

#### d) Chromaticity Region & Coordinates

Region	CIE x	CIE y	Region	CIE x	CIE y
<b>P rank (6500 K)</b>					
P1	0.3068	0.3113	P4	0.3135	0.3256
	0.3145	0.3187		0.3216	0.3334
	0.3135	0.3256		0.3210	0.3408
	0.3055	0.3177		0.3126	0.3324
P2	0.3145	0.3187	P7	0.3081	0.3049
	0.3221	0.3261		0.3154	0.3119
	0.3216	0.3334		0.3145	0.3187
	0.3135	0.3256		0.3068	0.3113
P3	0.3055	0.3177	P8	0.3154	0.3119
	0.3135	0.3256		0.3226	0.3188
	0.3126	0.3324		0.3221	0.3261
	0.3041	0.3240		0.3145	0.3187

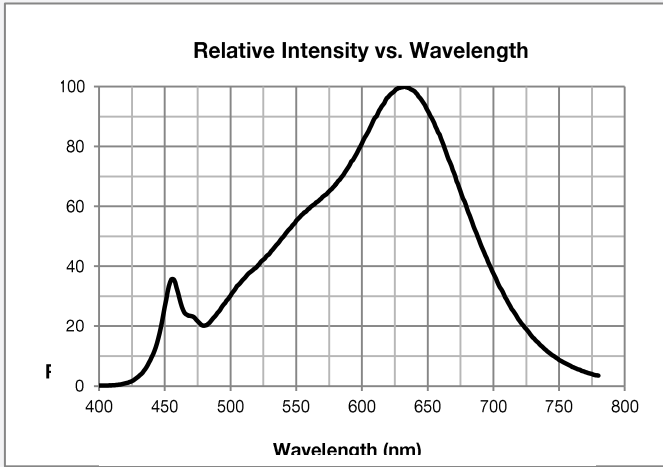
**Note:**

Samsung maintains measurement tolerance of:  $C_x, C_y = \pm 0.005$

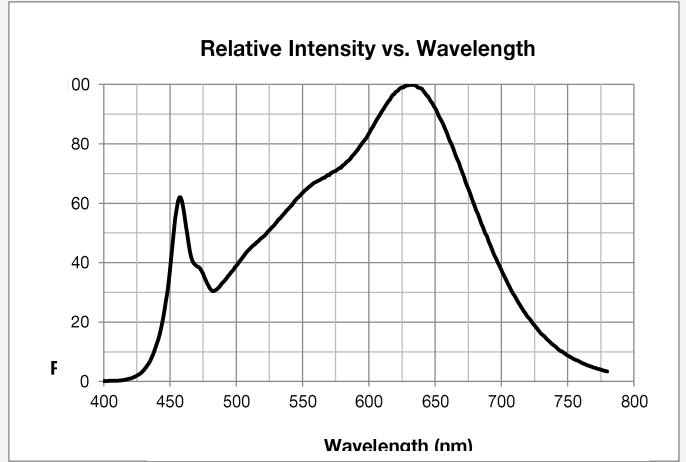
### 3. Typical Characteristics Graphs

#### a) Spectrum Distribution ( $I_f = 150 \text{ mA}$ , $T_s = 85 \text{ }^\circ\text{C}$ )

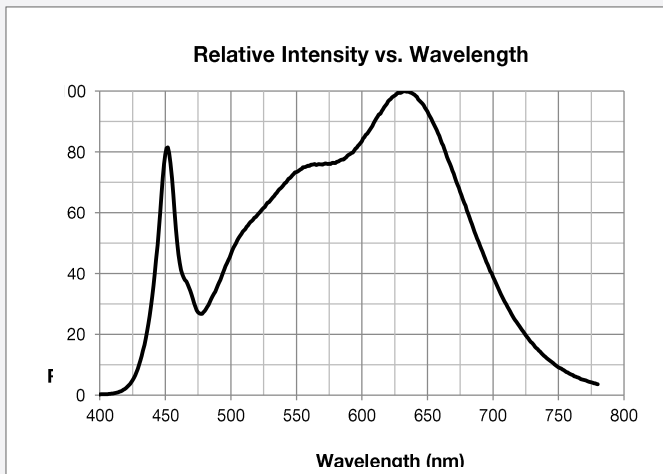
CCT: 2700 K



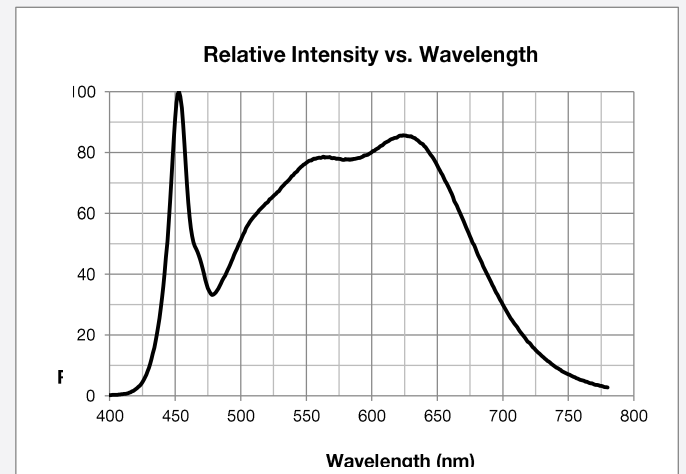
CCT: 3000 K



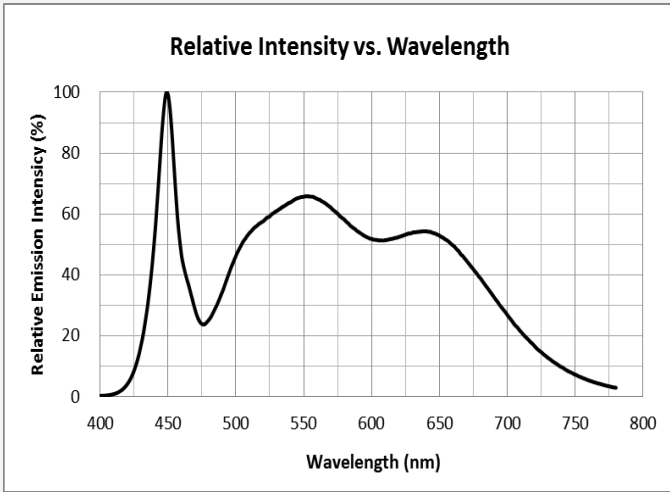
CCT: 3500 K



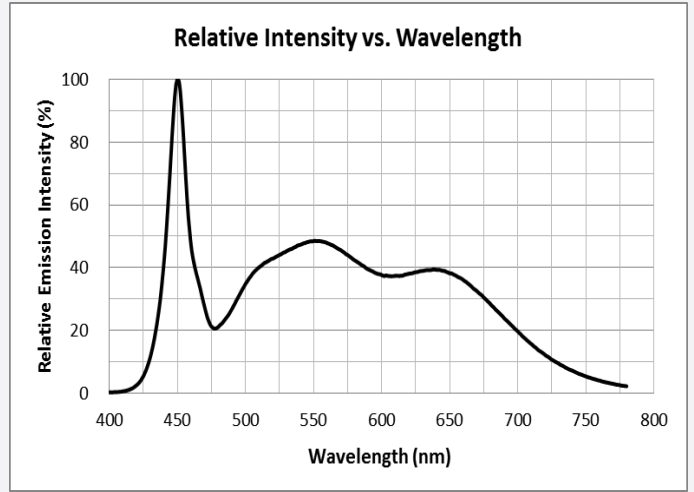
CCT: 4000 K



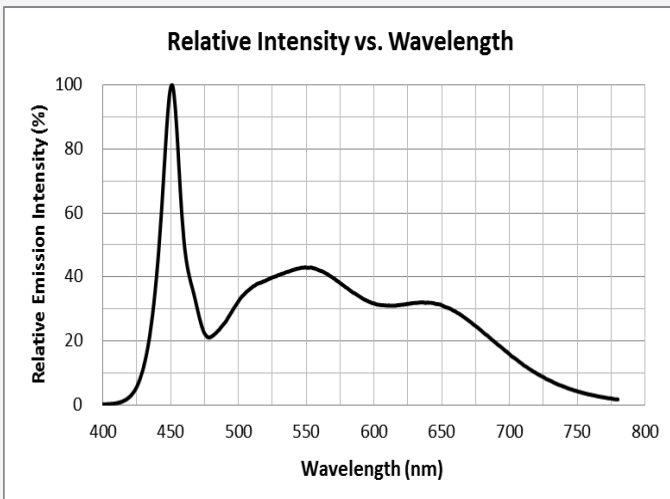
CCT: 5000 K



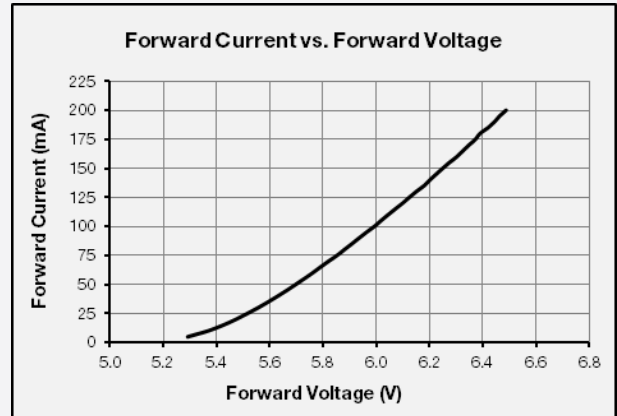
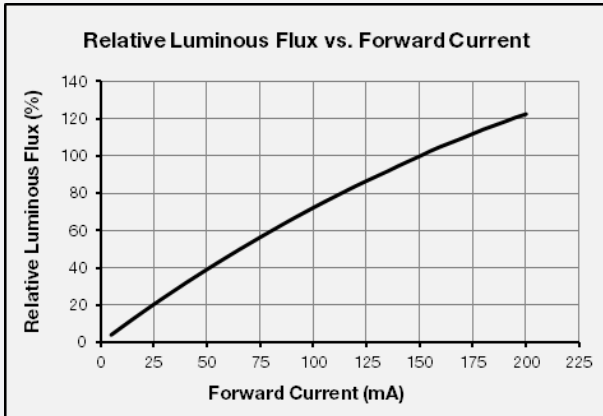
CCT: 5700 K



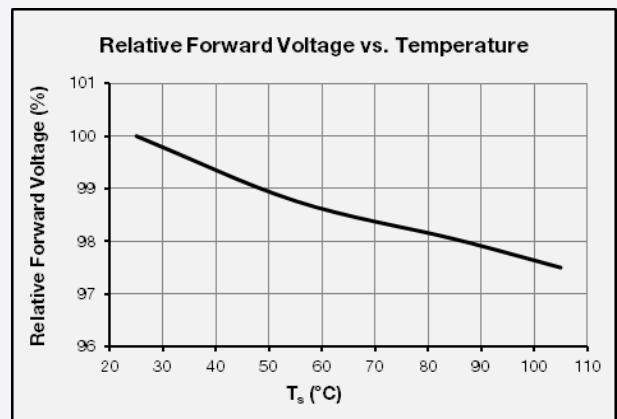
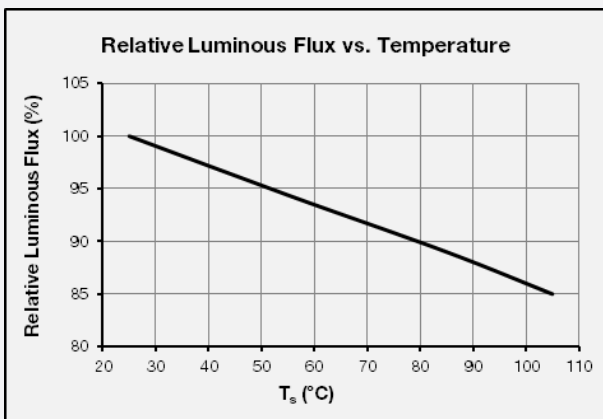
CCT: 6500K



b) Forward Current Characteristics ( $T_s = 85^\circ\text{C}$ )



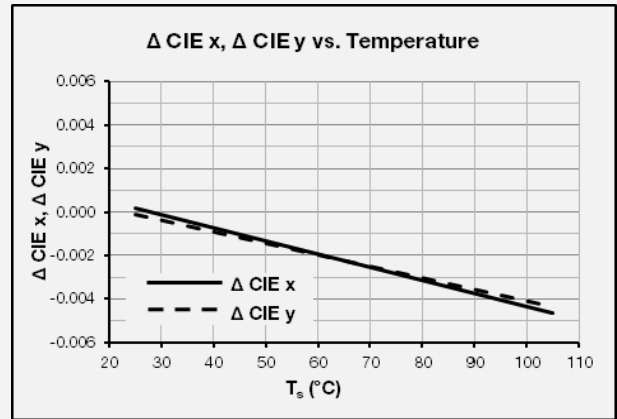
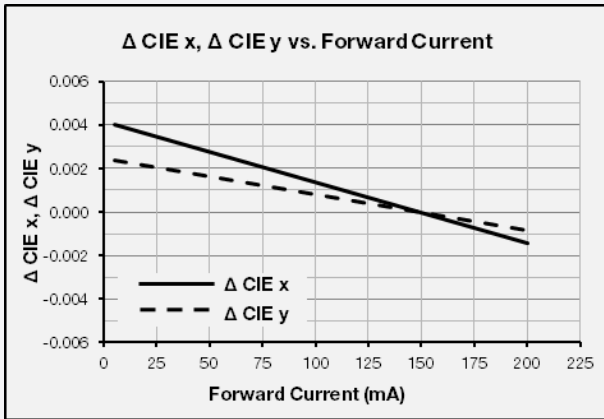
c) Temperature Characteristics ( $I_f = 150\text{ mA}$ )



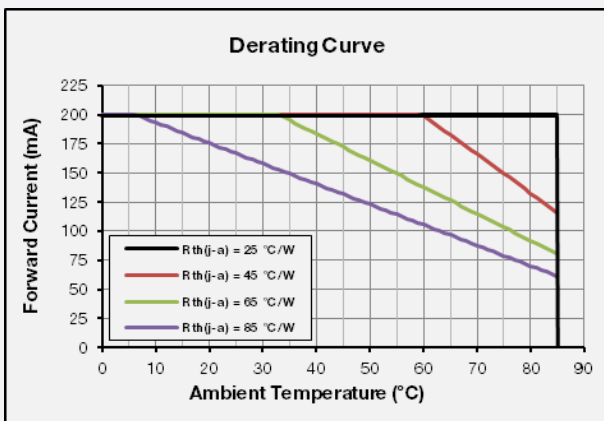
d) Color Shift Characteristics

$T_s = 85\text{ }^\circ\text{C}$

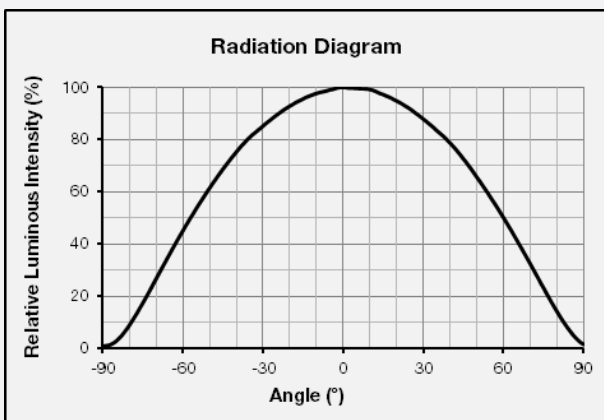
$I_F = 150\text{ mA}$



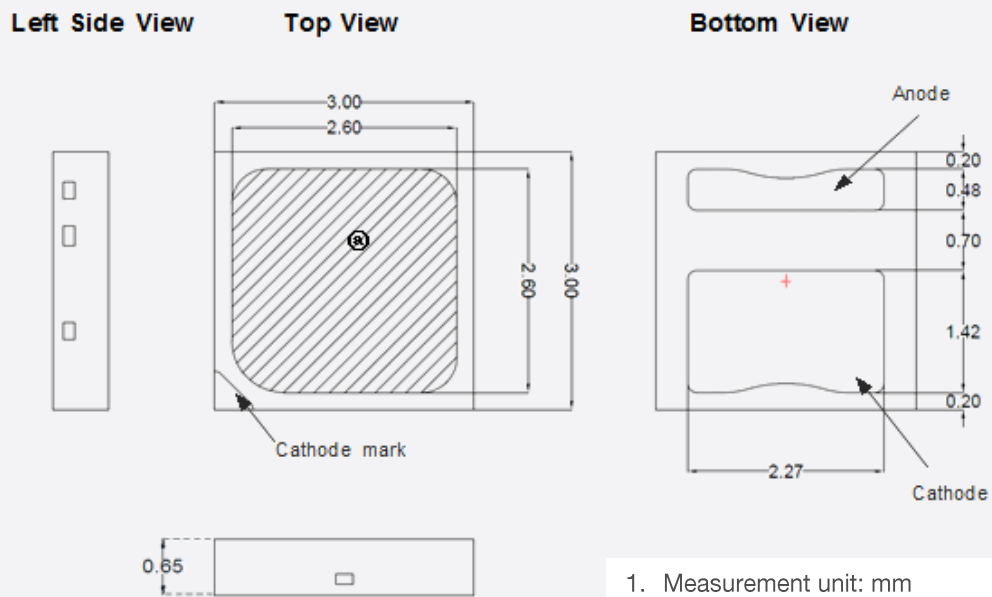
e) Derating Curve



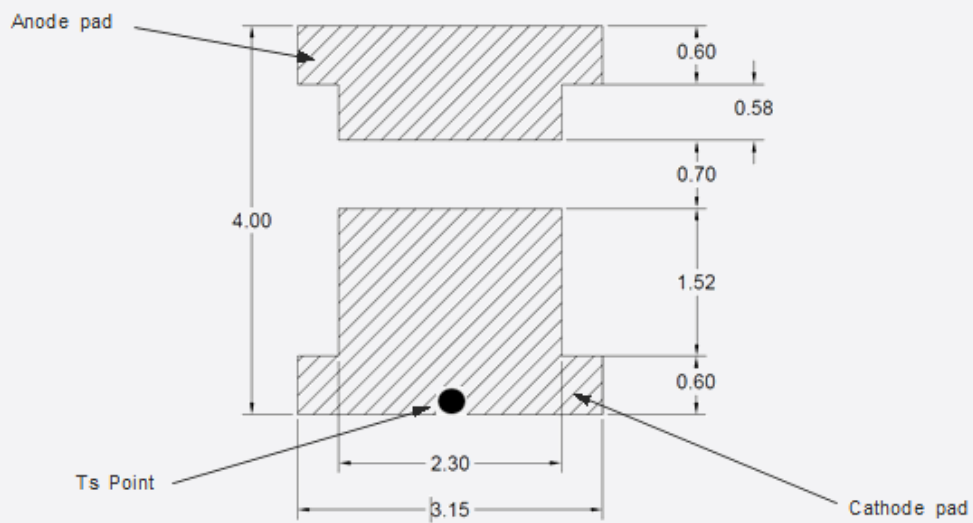
f) Beam Angle Characteristics ( $I_F = 150\text{ mA}$ ,  $T_s = 85\text{ }^\circ\text{C}$ )



#### 4. Outline Drawing & Dimension



1. Measurement unit: mm
2. Tolerance:  $\pm 0.10$  mm
3. Do not place pressure on the encapsulation resin ②



**Recommended Land Pattern**

#### Notes:

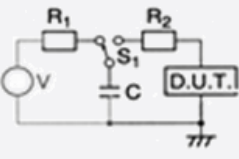
- 1) This LED has built-in ESD protection device(s) connected in parallel to LED chip(s).
- 2)  $T_s$  point and measurement method:
  - ① Measure one point at the cathode pad. If necessary, remove PSR of PCB to reach  $T_s$  point.
  - ② All pads must be soldered to the PCB to dissipate heat properly, otherwise the LED can be damaged.

**Precautions:**

- 1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

## 5. Reliability Test Items and Conditions

### a) Test Items

Test Item	Test Condition	Test Hour / Cycle	Sample Size	
Room Temperature Life Test	25 °C, DC 200 mA	1000 h	22	
High Temperature Life Test	85 °C, DC 200 mA	1000 h	22	
High Temperature Humidity Life Test	85 °C, 85 % RH, DC 200 mA	1000 h	22	
Low Temperature Life Test	-40 °C, DC 200 mA	1000 h	22	
Powered Temperature Cycle Test	-45 °C / 20 min ↔ 85 °C / 20 min, sweep 100 min cycle on/off: each 5 min, DC 200 mA	100 cycles	22	
Thermal Cycle	-45 °C / 15 min ↔ 125 °C / 15 min → Hot plate 180 °C	500 cycles	100	
High Temperature Storage	120 °C	1000 h	11	
Low Temperature Storage	-40 °C	1000 h	11	
ESD (HBM)		R <sub>1</sub> : 10 MΩ R <sub>2</sub> : 1.5 kΩ C: 100 pF V: ±5 kV	5 times	30
ESD (MM)				
Vibration Test	20~2000~20 Hz, 200 m/s <sup>2</sup> , sweep 4 min X, Y, Z 3 direction, each 1 cycle	4 cycles	11	
Mechanical Shock Test	1500 g, 0.5 ms 3 shocks each X-Y-Z axis	5 cycles	11	

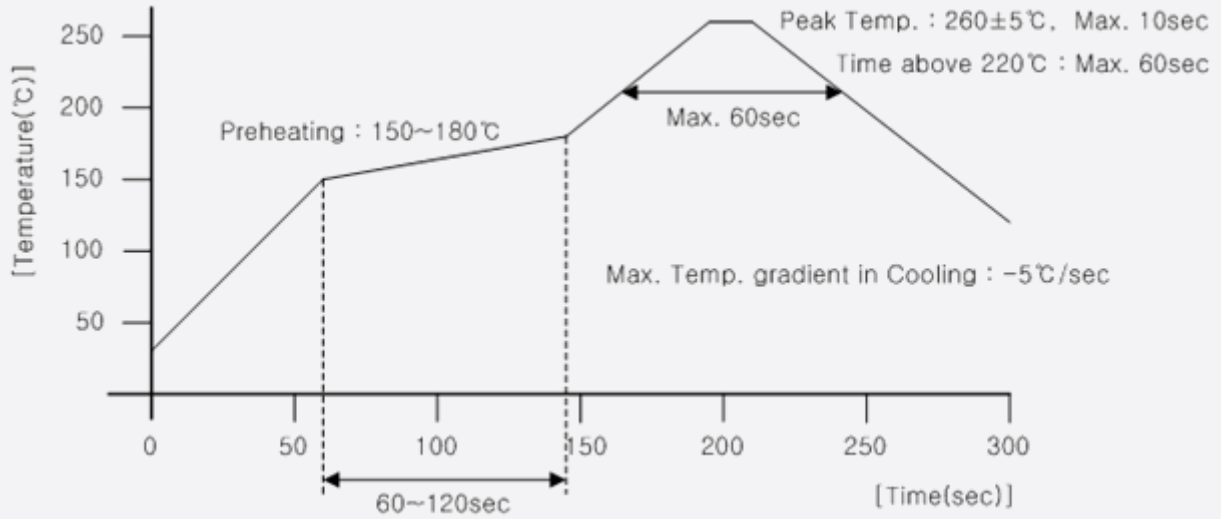
### b) Criteria for Judging the Damage

Item	Symbol	Test Condition (T <sub>s</sub> = 25 °C)	Limit	
			Min.	Max.
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> = 150 mA	Init. Value * 0.9	Init. Value * 1.1
Luminous Flux	Φ <sub>v</sub>	I <sub>F</sub> = 150 mA	Init. Value * 0.7	Init. Value * 1.1

## 6. Soldering Conditions

### a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.



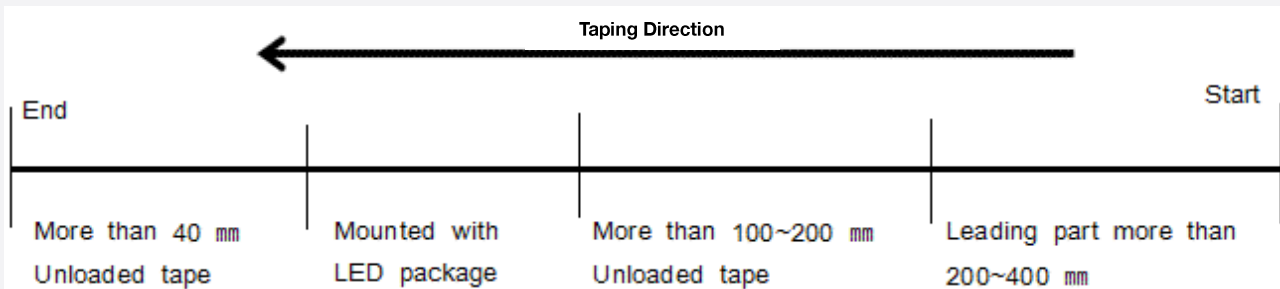
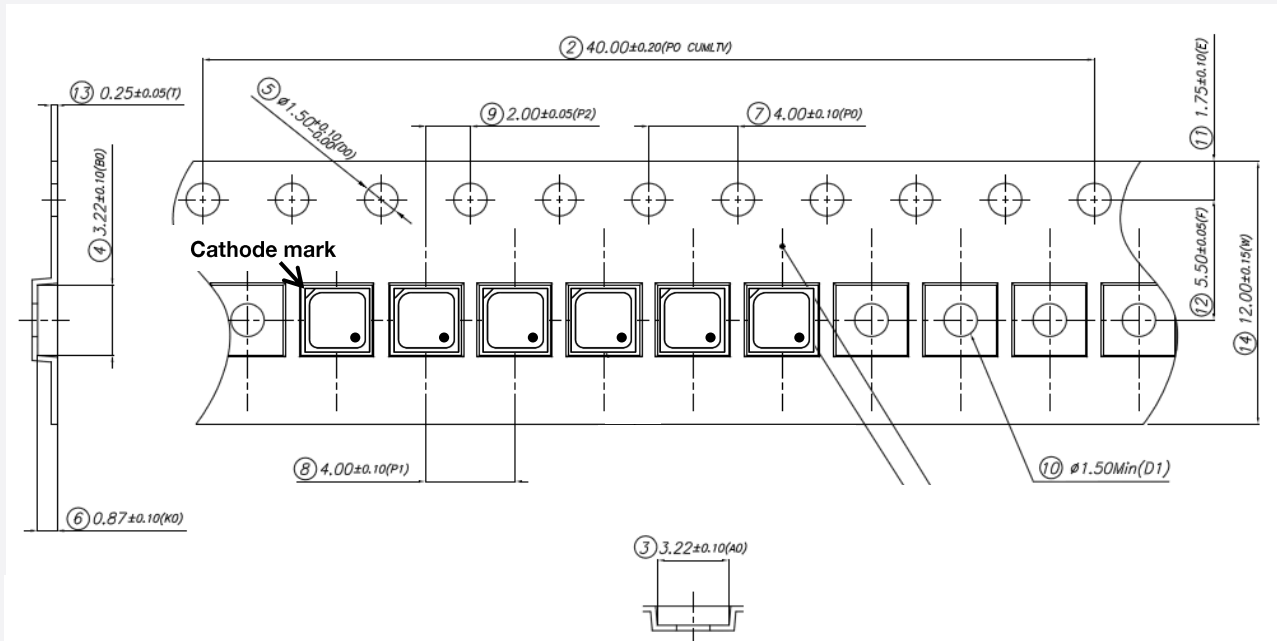
### b) Manual Soldering Conditions

Not more than 5 seconds @ max. 300 °C, under soldering iron.

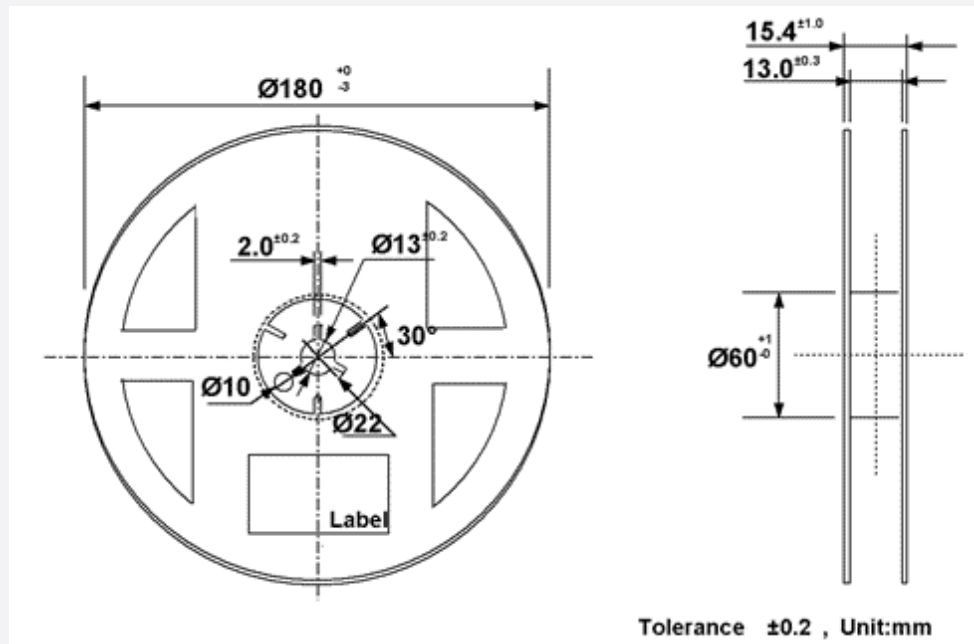
## 7. Tape & Reel

### a) Taping Dimension

(unit: mm)



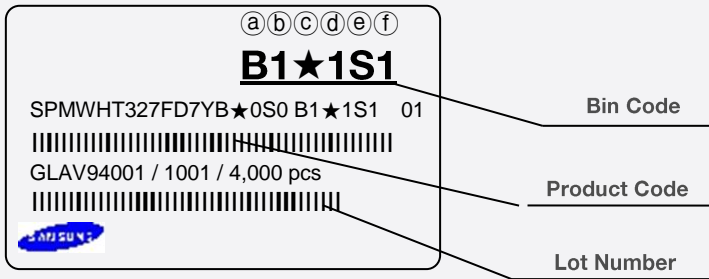
## b) Reel Dimension

**Notes:**

- 1) Quantity: The quantity/reel is 4,000 pcs
- 2) Cumulative tolerance: Cumulative tolerance / 10 pitches is  $\pm 0.2$  mm
- 3) Adhesion strength of cover tape: Adhesion strength is 0.1-0.7 N when the cover tape is turned off from the carrier tape at  $10^\circ$  angle to the carrier tape
- 4) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

## 8. Label Structure

### a) Label Structure



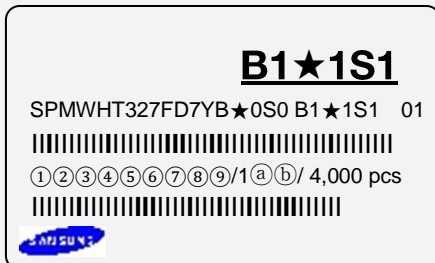
Note: Denoted bin code and product code above is only an example  
'★' means all kind of Chromaticity Coordinate Ranks

Bin Code:

- ⒶⒷ: Forward Voltage bin (refer to page 7)
- ⒸⒹ: Chromaticity bin (refer to page 9~12)
- ⒺⒻ: Luminous Flux bin (refer to page 4-5)

### b) Lot Number

The lot number is composed of the following characters:



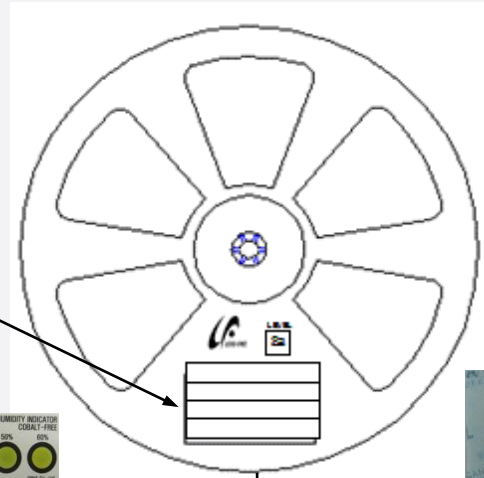
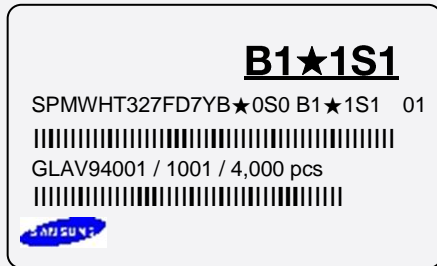
①②③④⑤⑥⑦⑧⑨ / 1ⒶⒷⒸ / 4,000 pcs

- ① : Production site (S: Giheung, Korea, G: Tianjin, China)
- ② : L (LED)
- ③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)
- ④ : Year (Y: 2014, Z: 2015, A: 2016, ...)
- ⑤ : Month (1~9, A, B, C)
- ⑥ : Day (1~9, A, B~V)
- ⑦⑧⑨ : Product serial number (001 ~ 999)
- ⒶⒷⒸ : Reel number (001 ~ 999)

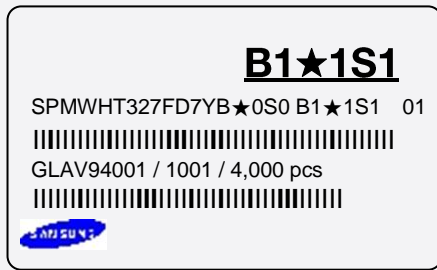
## 9. Packing Structure

### a-1) Packing Process

Reel



Aluminum Vinyl Packing Bag

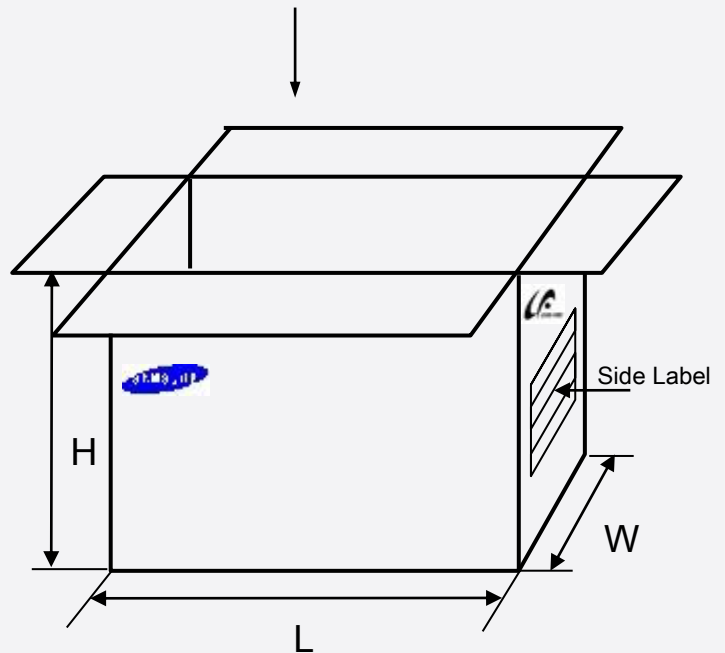
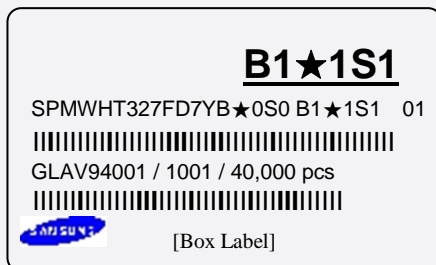


Outer Box


Material: Paper (SW3B(B))

Type	Size (mm)			Note
	L	W	H	
7 inch L	245 ± 5	220 ± 5	182 ± 5	Up to 10 reels
7 inch S	245 ± 5	220 ± 5	86 ± 5	Up to 5 reels

Side Label



b) Aluminum Vinyl Packing Bag



**CAUTION**  
 This bag contains  
**MOISTURE SENSITIVE DEVICES**

**LEVEL**  
2a

1. Shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
2. Peak package body temperature: 240 °C
3. After this bag is opened, devices that will be subjected to reflow solder or other high temperature processes must be:
  - a. Mounted within 672 hours at factory conditions of equal to or less than 30°C /60% RH, or
  - b. Stored at <10% RH
4. Devices require bake, before mounting, if:
  - a. Humidity Indicator Card is >60% when read at 23±5°C, or
  - b. 2a is not met.
5. If baking is required, devices must be baked for 10 - 24 hours at 60±5°C

Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure.

Bag seal due date: \_\_\_\_\_  
 (If blank, see code label)

Note: Level and body temperature by IPC/JEDEC J-STD-020


B1★1S1



SPMWHT327FD7YB★0S1 B1★1S1 01


|||||

GLAV94001 / 1001 / 4,000 pcs


|||||





**ATTENTION**  
 OBSERVE PRECAUTIONS  
 FOR HANDLING  
 ELECTROSTATIC  
 SENSITIVE  
 DEVICES



**■ 주의 사항**

이 알루미늄 지퍼 백은 습기 및 정전기로부터 제품을 보호하기 위하여 제작되었습니다. 개봉 후에는 즉시 솔더 작업을 실시하는 것을 권장합니다.

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**■ Important**

This Al Zipper bag is designed to protect the enclosed products from moisture and ESD. Once opened, the products should be soldered onto the printed circuit board immediately. When not in use, please do not leave the products unprotected by the Al Zipper Bag. To repack unused products., please ensure the zip-lock is completely sealed with the dry pack left inside.

c) Silica Gel & Humidity Indicator Card inside Aluminum Vinyl Bag



## 10. Precautions in Handling & Use

- 1) For over-current protection, users are recommended to apply resistors connected in series with the LEDs to mitigate sudden change of the forward current caused by shift of forward voltage.
- 2) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
- 3) When the device is in operation, the forward current should be carefully determined considering the maximum ambient temperature and corresponding junction temperature.
- 4) LEDs must be stored in a clean environment. If the LEDs are to be stored for three months or more after being shipped from Samsung, they should be packed with a nitrogen-filled container (shelf life of sealed bags is 12 months at temperature 0~40 °C, 0~90 % RH).
- 5) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
  - a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH, or
  - b. Stored at <10 % RH
- 6) Repack unused devices with anti-moisture packing, fold to close any opening and then store in a dry place.
- 7) Devices require baking before mounting, if humidity card reading is >60 % at 23 ± 5 °C.
- 8) Devices must be baked for 10~24 hours at 60 ± 5 °C, if baking is required.
- 9) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- 10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
- 11) Risk of sulfurization (or tarnishing)  
 The LED from Samsung uses a silver-plated lead frame and its surface color may change to black (or dark colored) when it is exposed to sulfur (S), chlorine (Cl) or other halogen compound. Sulfurization of lead frame may cause intensity degradation, change of chromaticity coordinates and, in extreme cases, open circuit. It requires caution. Due to possible sulfurization of lead frame, LED should not be used and stored together with oxidizing substances made of materials such as rubber, plain paper, lead solder cream, etc.

# Legal and additional information.

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